

Form 1449 (M d i f i d)

Information Disclosure
Statement By Applicant

(Use Several Sheets if Necessary)

Atty. Docket No.

NNEX0004

Applicant:

Mok et al.

Filing Date:

February 20, 2002

Serial No.:

10/069,902

Group:

2815

Unassigned



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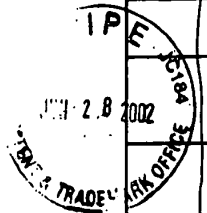
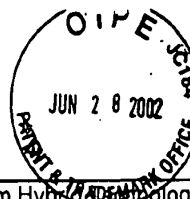
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